

Board Level Shielding (BLS) Components

Parker Chomerics Board Level Shielding (BLS) and stamped metal components are the optimal solution for reducing or limiting the effect of electromagnetic interference (EMI) on printed circuit boards. Developed based on decades of expertise in EMI and RF shielding, precision metal forming, and state-of-the-art manufacturing practices, Parker Chomerics BLS and stamped metal components are designed and manufactured to help provide isolation of board level components, minimize crosstalk, and reduce EMI susceptibility.

Parker Chomerics is a leading producer of innovative technologies and services, providing global solutions for:

- EMI and thermal interface material development
- Application and engineering support
- EMI/RF emissions testing
- Fast and cost-effective prototyping



TYPICAL APPLICATIONS:

- High Connectivity and Wi-Fi equipment
- Smart home and smart devices
- Laptops, tablets, and smart phones
- Streaming media players
- Telecommunications and 5G infrastructure
- Automotive electronics and control modules

PRODUCT FEATURES:

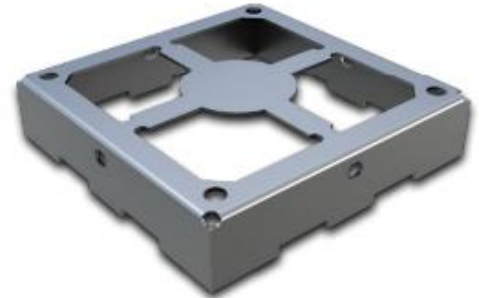
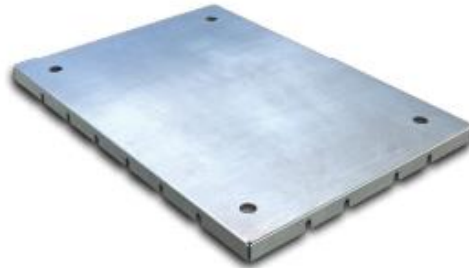
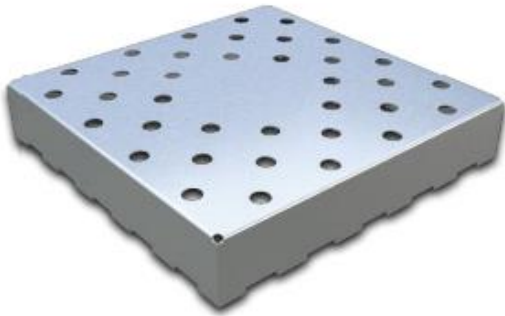
- Highly customizable
- Economical
- High volume production
- Design flexibility
- Excellent high frequency EMI/RF shielding
- High speed assembly integration



Authorized Canadian Partner



Board Level Shielding (BLS) Components



Design options can include onepiece, two-piece and multicavity configurations, while also incorporating precise mounting methods such as surface mount technology (SMT). RF shielding components are manufactured using either a stamping/forming or a drawing process based on specific design criteria and end application needs. Board level shields can also integrate unique design features including, but not limited to, ventilation holes, complex geometries, embossing, and orientation markings. Parker Chomerics BLS products are available in several base materials as well as plating options, including:

- Tin-Plated Cold Rolled Steel
- Nickel Silver
- Aluminum
- Stainless Steel Other materials and plating options are available on request.

COMPONENT INTEGRATION:

Board level shields are often a single part of a complex assembly and must be seamlessly integrated into full PCB builds. They can be integrated with all kinds of products for ease of assembly and reduced supply chain

- Thermal gap pads
- RF absorbing coatings
- Electrical grounding materials
- Heatsinks



Authorized Canadian Partner

